

Z21 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22 ■These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

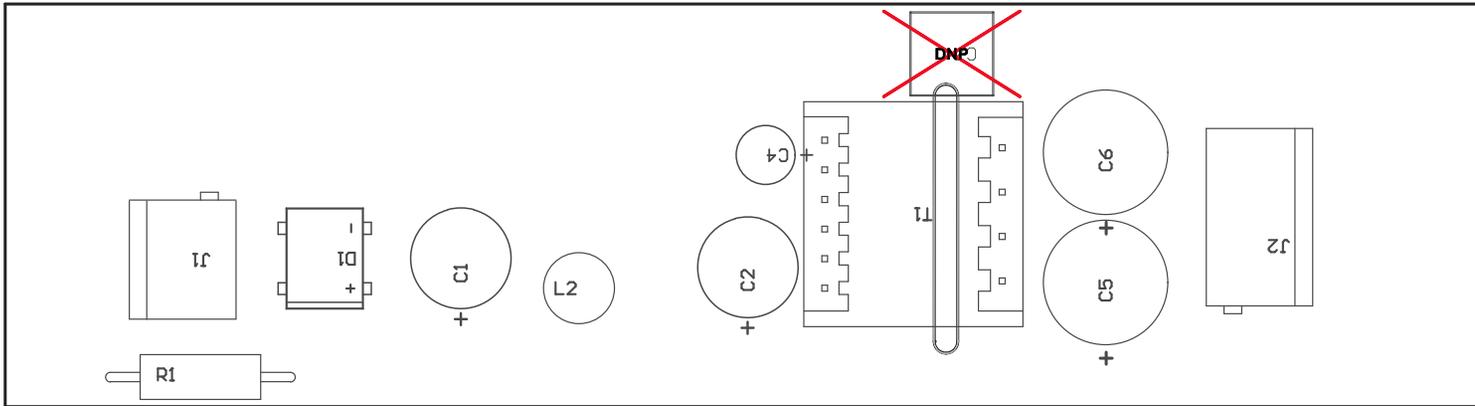
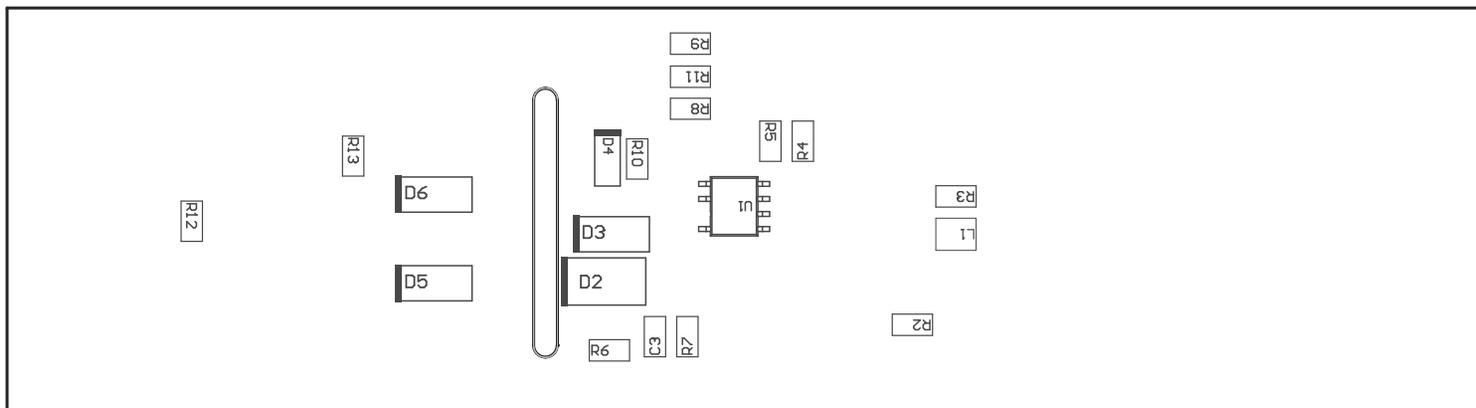


TABLE 1

Variant	Label text
001	UCC28911 Dual Output Flyback
002	ChangeMe!

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00618	REV: E1	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 07/07/2015 14:38:30	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00618	REV: E1	SVN REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 07/07/2015 14:38:31	TEXAS INSTRUMENTS	

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